

IEEE ECCE ASIA 2021

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Hybrid Mode of Conference

Singapore

Sanjib Kumar Panda

**R-10, Chair, Membership & Chapter Development,
IEEE - PELS**

Director, Power & Energy, Dept. of ECE, NUS, Singapore
Presentation at ECCE NA, Virtual, 16th October 2020

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Timelines of the Conference Organization

■ *Current Status:*

- Digest Submission : 149
- Special Session Proposals : 11


■ *Key deadlines:*

- Deadline for submissions of digests or abstracts or presentations or papers : ~~30 Sep. 2020~~ 21 Oct. 2020
- Notification of acceptance : 1 Jan. 2021
- Deadline for final manuscripts : 15 Feb. 2021





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you for
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